

FIG. 1

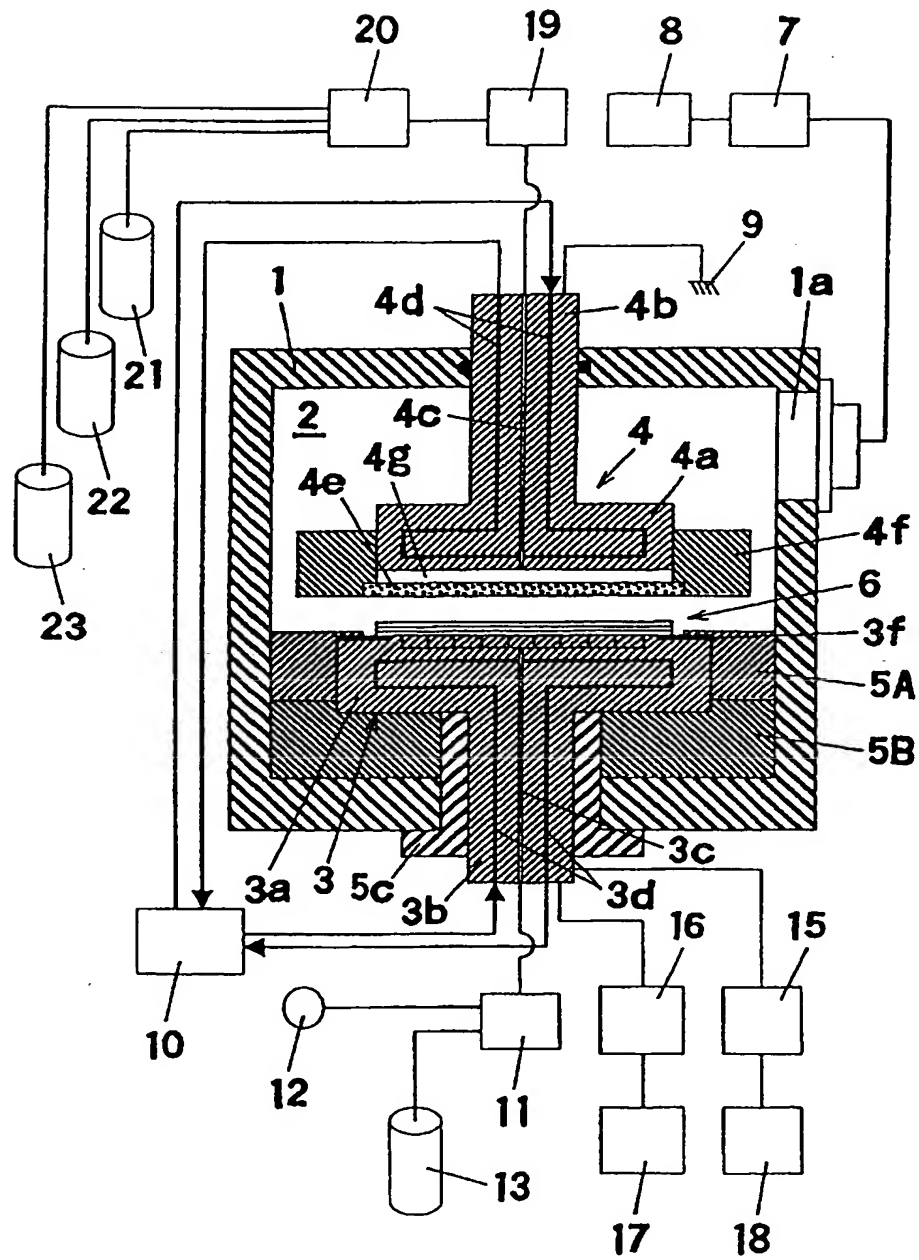


FIG. 2

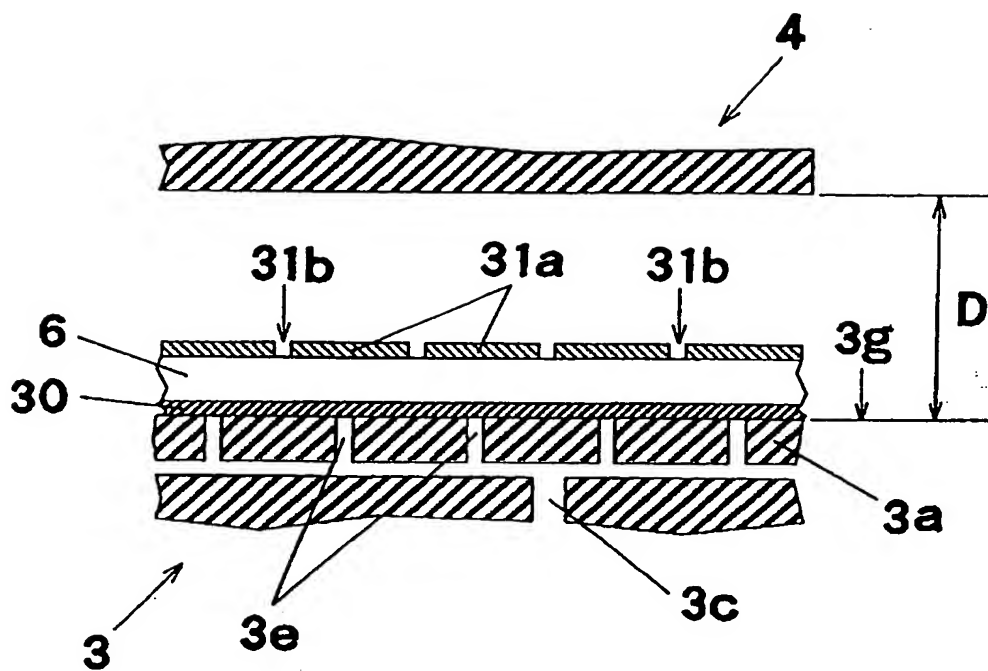


FIG. 3 (a)

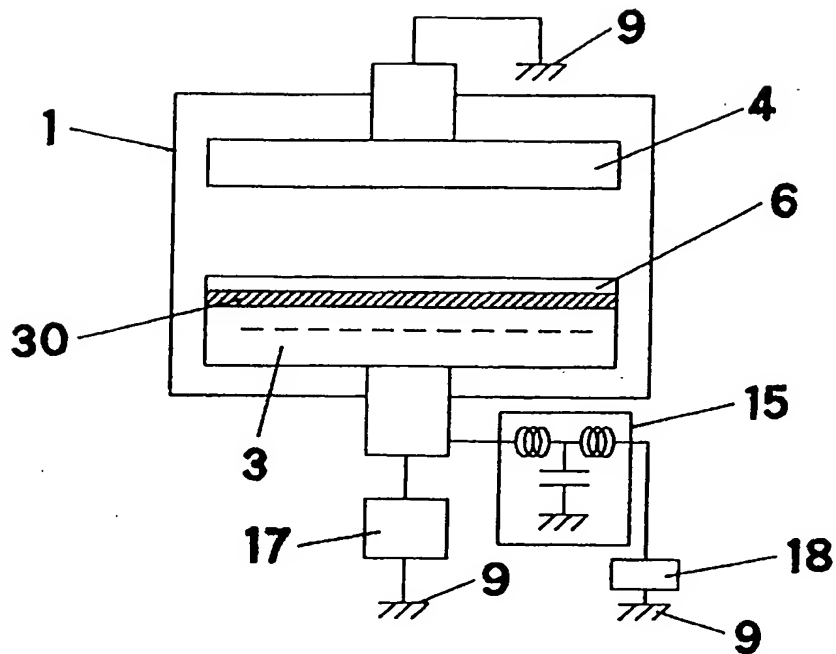


FIG. 3 (b)

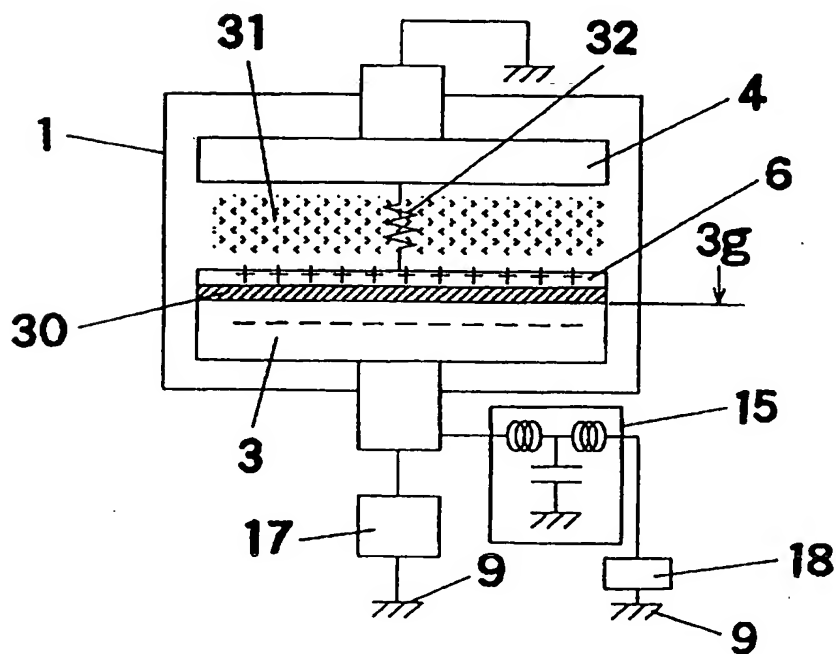


FIG. 4

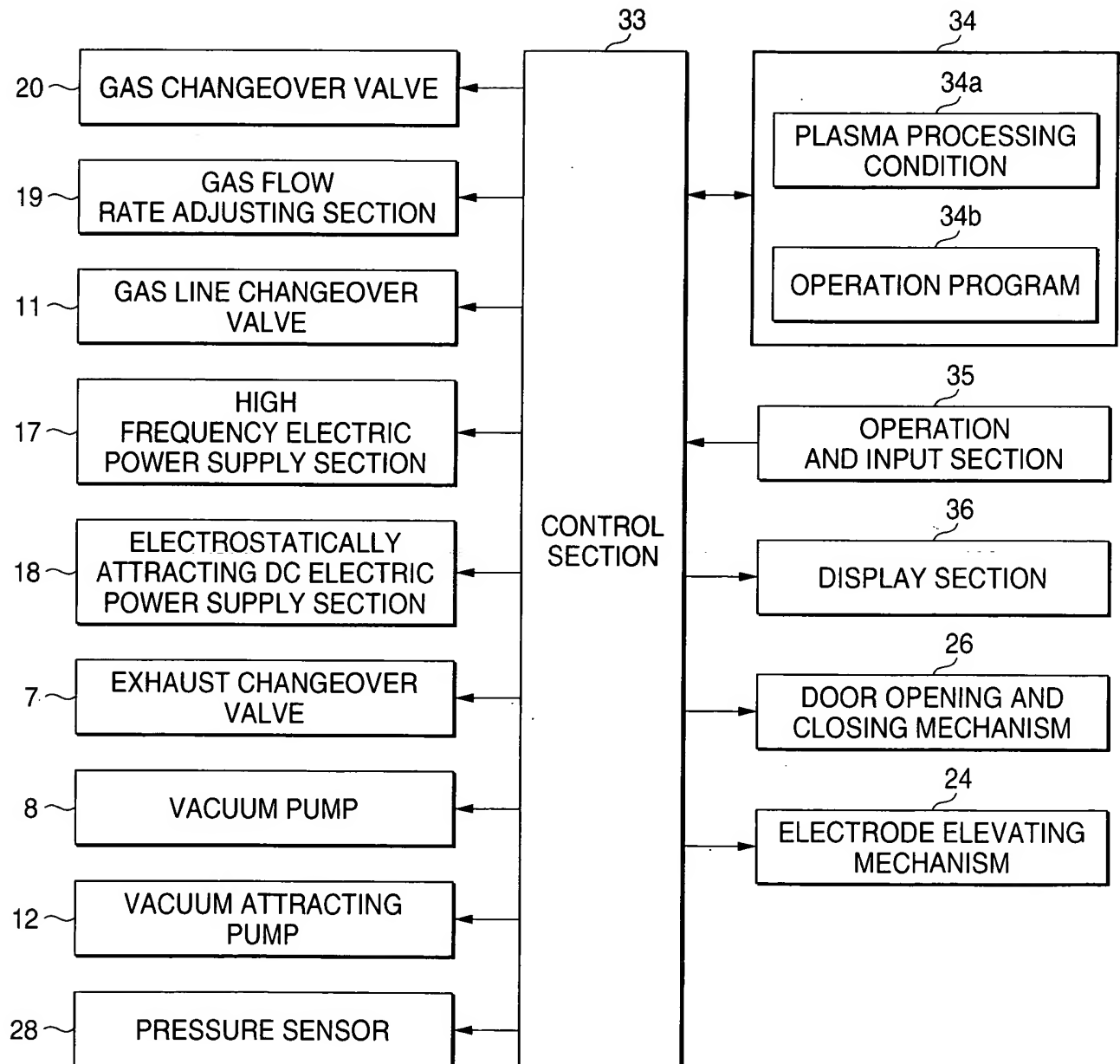


FIG. 5 (a)

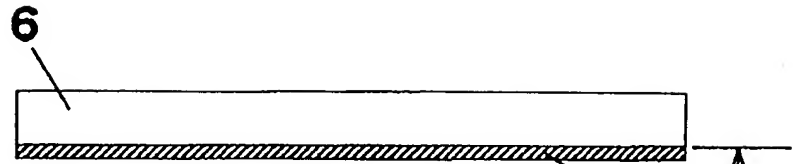


FIG. 5 (b)

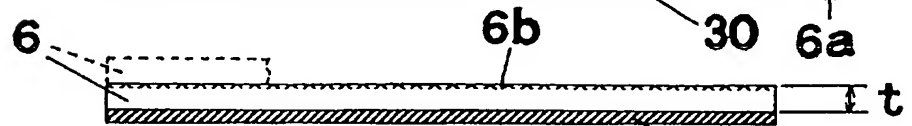


FIG. 5 (c)

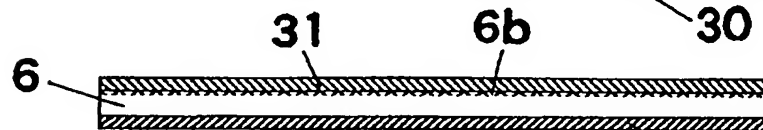


FIG. 5 (d)

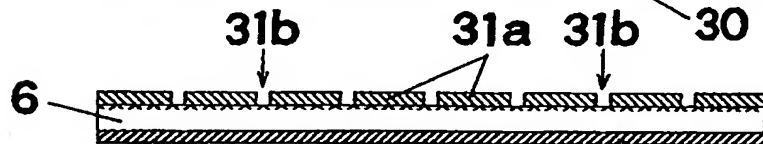


FIG. 5 (e)

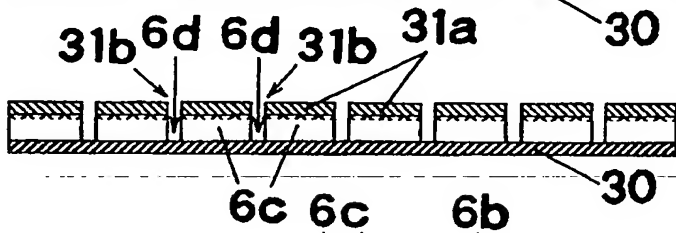


FIG. 5 (f)



FIG. 5 (g)



FIG. 5 (h)

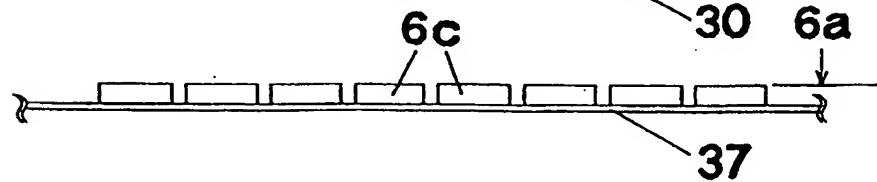


FIG. 6

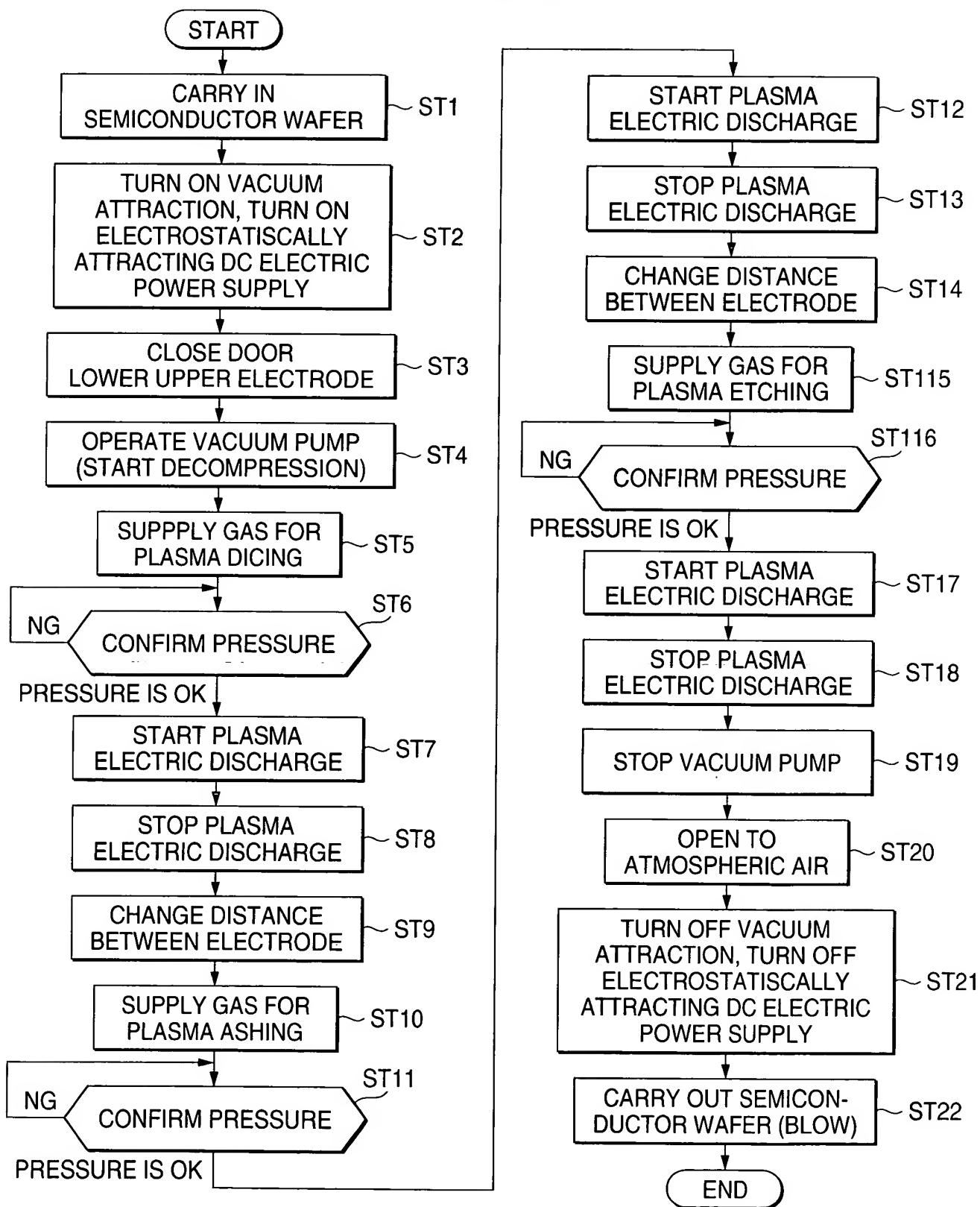


FIG. 7

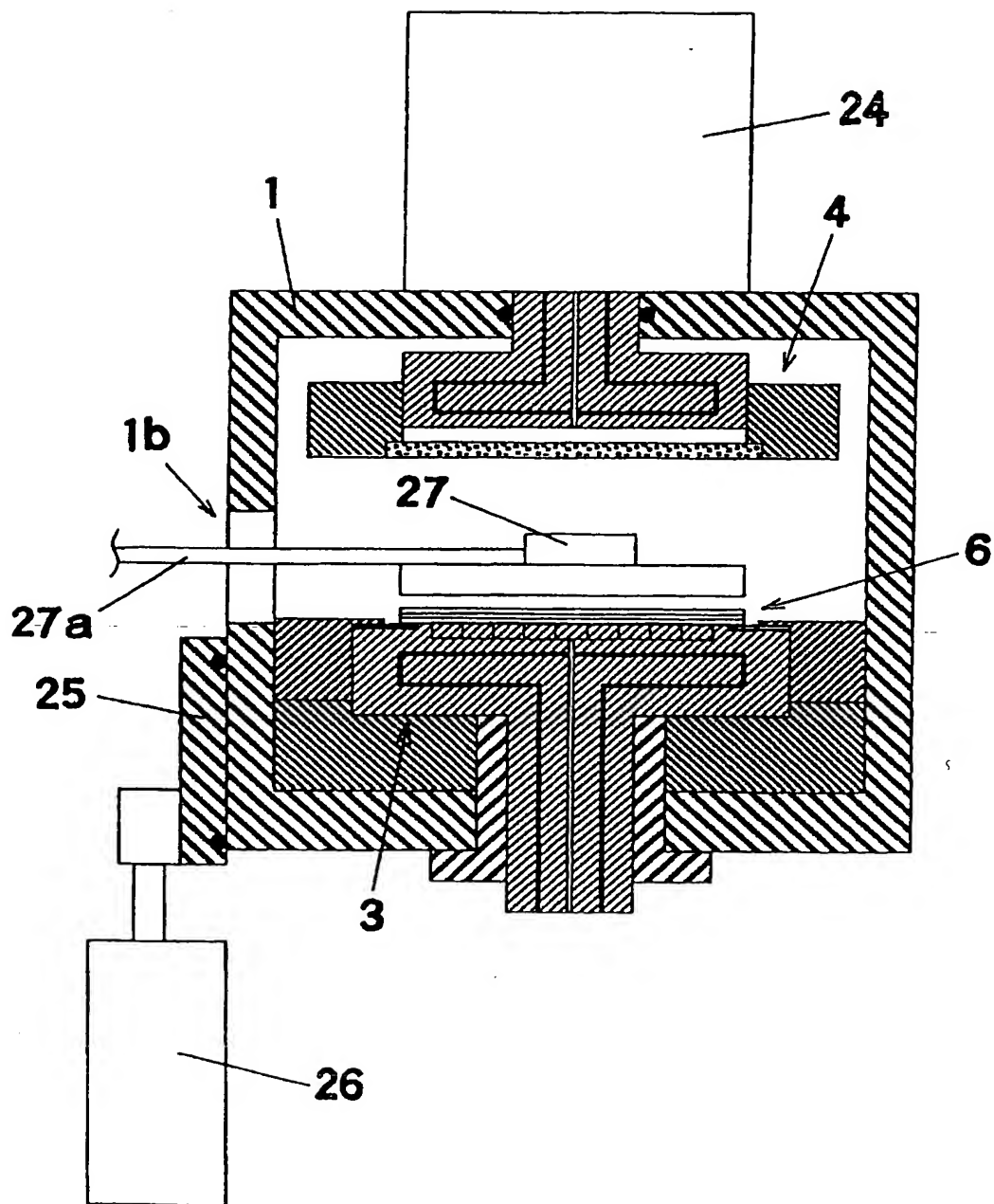


FIG. 8

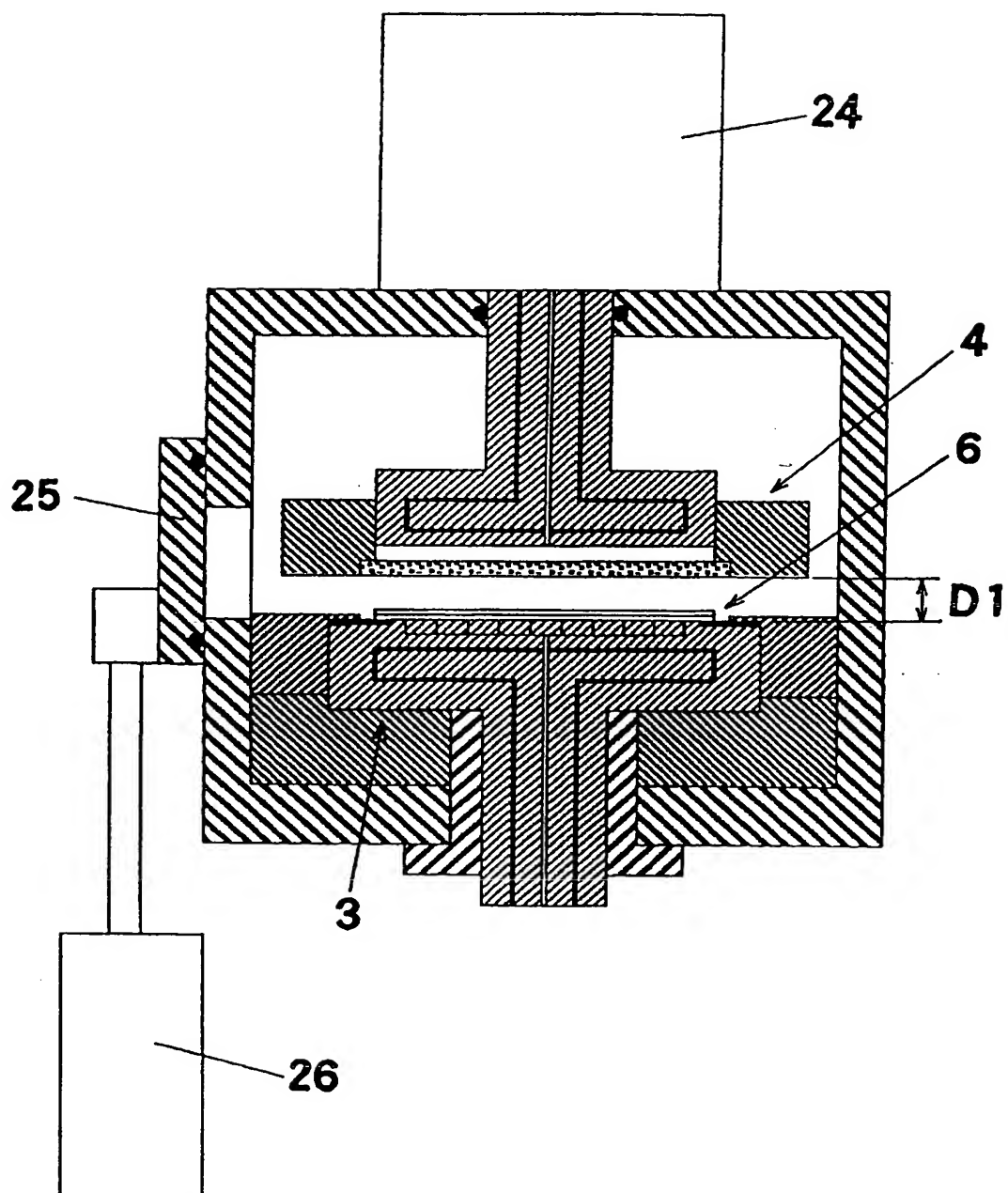




FIG. 9

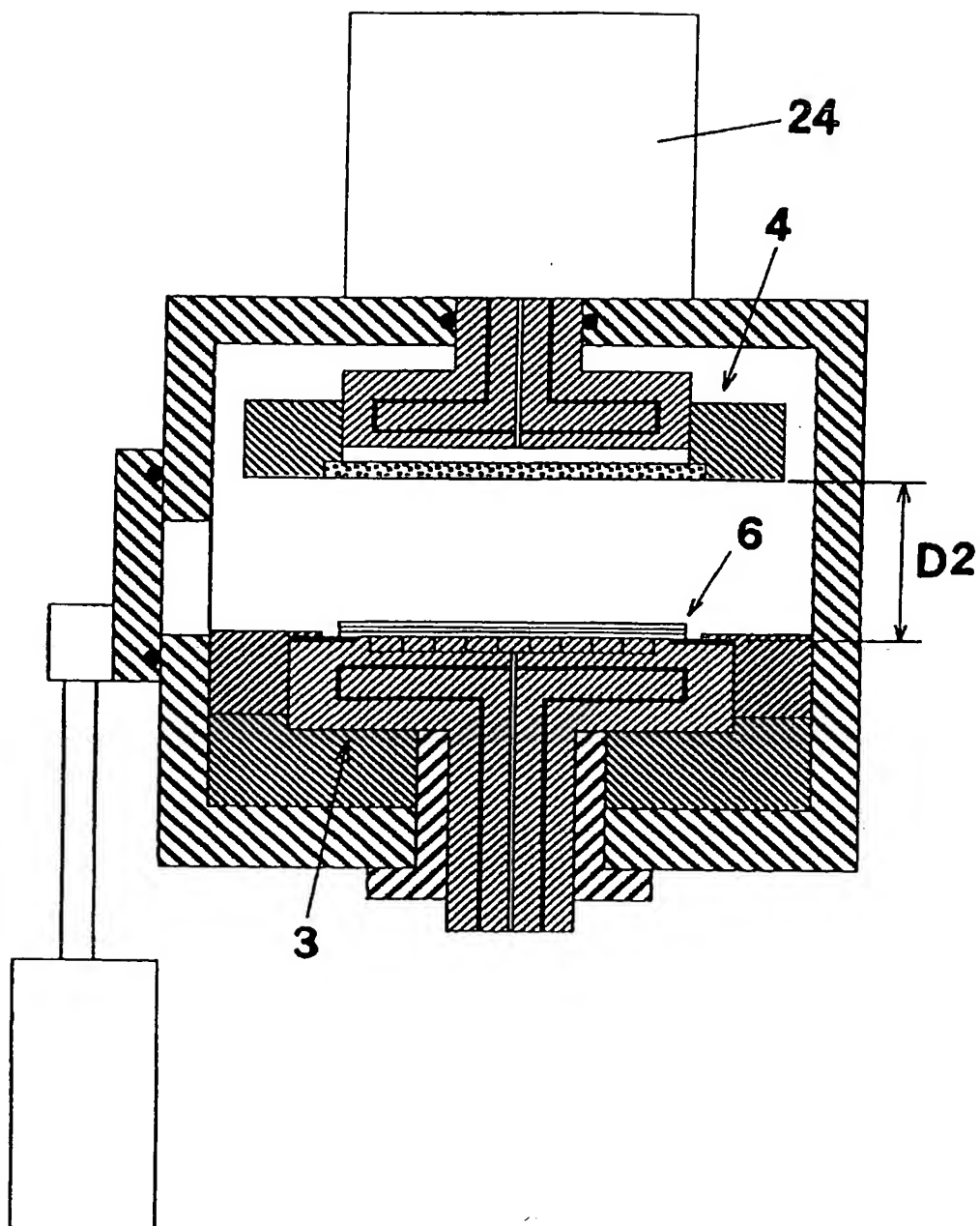
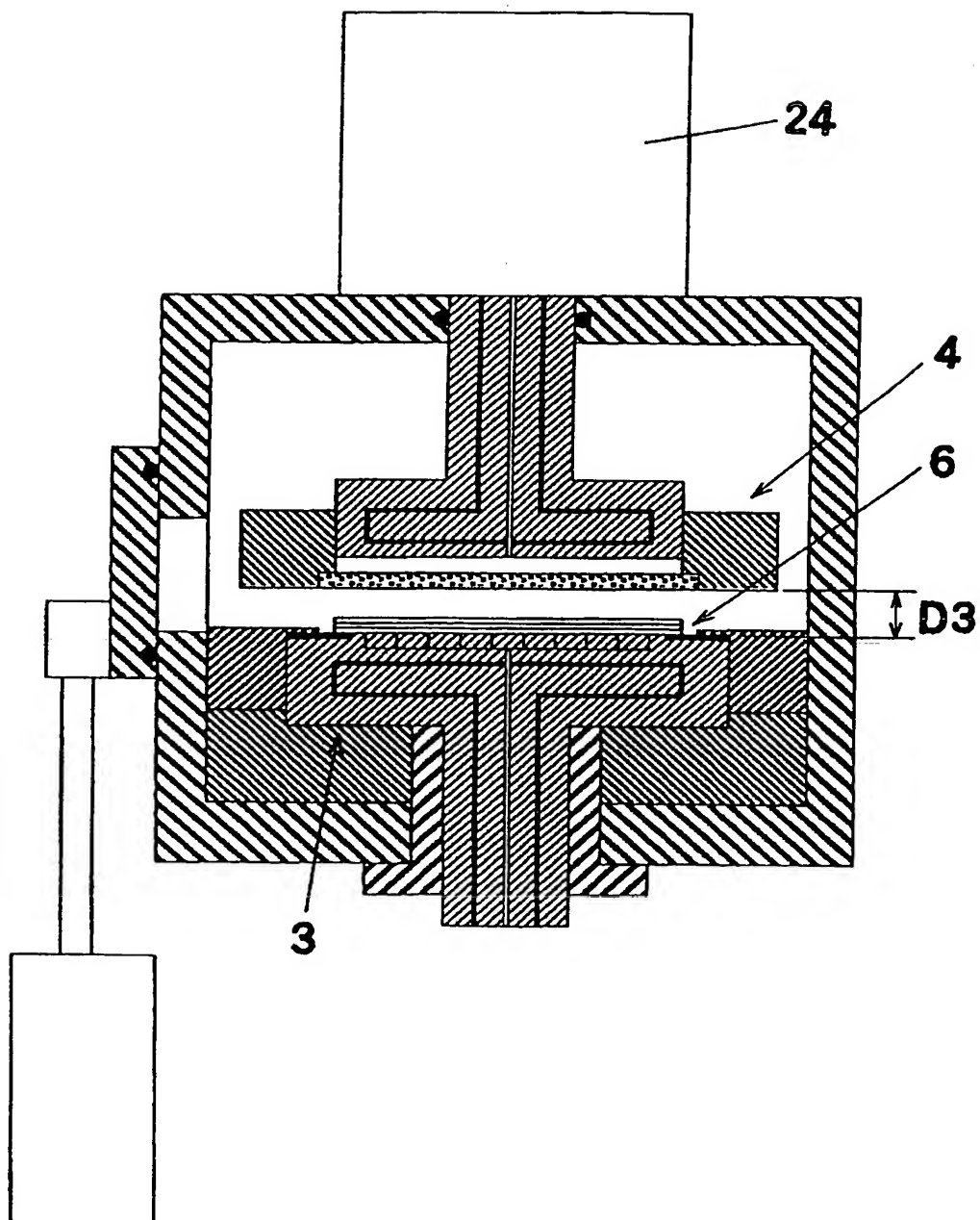


FIG. 10





11/11

**FIG. 11**

PROCESS	RF POWER (W)	PRESSURE (Pa)	DISTANCE BETWEEN ELECTRODE (mm)
PLASMA DICING ↓	500-3000	5-300	5-50
ASHING ↓	100-1000	5-100	50-100
PLASMA STRESS RELIEF	500-3000	300-2000	5-20